

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: **10/829,060** Examiner: **Hoa Cao Nguyen**
Inventor: **Su-Tsai Lu, Shu-Ming Chang, Shyh-Ming Chang, Yao-Sheng Lin and**
Yuan-Chang Huang
Filed: **04/20/2004** Art Unit: **2841**
Title: **Bonding Structure With Buffer Layer And Method Of Forming The**
Same

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT A

In response to the Office Action mailed **08/23/2006**, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks begin on page 7 of this paper.